D3

D2 12

D1 **[**3

D0 **[**] 4

W 6

G

GND 8

ΥΠ<sub>5</sub>

Π7

**E OR M PACKAGE** (TOP VIEW)

16**1** Vcc

15 D4

14 D5

13 D6

12 D7

11 🛛 A

10 B

9 C

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- AC Types Feature 1.5-V to 5.5-V Operation and Balanced Noise Immunity at 30% of the Supply Voltage
- 8-Line to 1-Line Multiplexers Can Perform as:
  - Boolean Function Generators
  - Parallel-to-Serial Converters
  - Data Source Selectors
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- **Balanced Propagation Delays**
- ±24-mA Output Drive Current - Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and **Circuit Design**
- **Exceeds 2-kV ESD Protection Per** • MIL-STD-883, Method 3015

### description/ordering information

This data selector/multiplexer provides full binary decoding to select one of eight data sources. The strobe (G) input must be at a low logic level to enable the inputs. A high level at the strobe terminal forces the W output high and the Y output low.

TA	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING							
–55°C to 125°C	PDIP – E	Tube	CD74AC151E	CD74AC151E							
	SOIC – M	Tape and reel	CD74AC151M96	AC151M							

### **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

	FUNCTION TABLE							
	11	NPUTS	-	OUT	PUTS			
	SELECT	-	STROBE	v	w			
С	В	Α	G	I	vv			
Х	Х	Х	Н	L	Н			
L	L	L	L	D0	D0			
L	L	Н	L	D1	D1			
L	н	L	L	D2	D2			
L	н	Н	L	D3	D3			
н	L	L	L	D4	D4			
н	L	Н	L	D5	D5			
н	Н	L	L	D6	D6			
н	Н	Н	L	D7	D7			

D0, D1 . . . D7 = the level of the respective D input



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

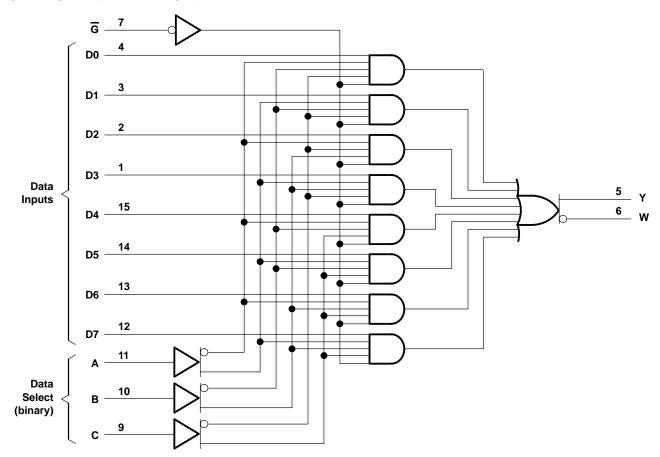
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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### logic diagram (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>	–0.5 V to 6 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	±20 mA
Output clamp current, $I_{OK}$ (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> ) (see Note 1)	±50 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): E package	67°C/W
M package	73°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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### recommended operating conditions (see Note 3)

			T <sub>A</sub> = 25°C		–55° 125		–40° 85°		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
VCC	Supply voltage		1.5	5.5	1.5	5.5	1.5	5.5	V
		V <sub>CC</sub> = 1.5 V	1.2		1.2		1.2		
VIH	High-level input voltage	$V_{CC} = 3 V$	2.1		2.1		2.1		V
		V <sub>CC</sub> = 5.5 V	3.85		3.85		3.85		
		V <sub>CC</sub> = 1.5 V		0.3		0.3		0.3	
VIL	Low-level input voltage	$V_{CC} = 3 V$		0.9		0.9		0.9	V
		V <sub>CC</sub> = 5.5 V		1.65		1.65		1.65	
VI	Input voltage		0	VCC	0	VCC	0	VCC	V
VO	Output voltage		0	VCC	0	VCC	0	VCC	V
IOH	High-level output current	V <sub>CC</sub> = 4.5 V to 5.5 V		-24		-24		-24	mA
I <sub>OL</sub>	Low-level output current	$V_{CC}$ = 4.5 V to 5.5 V		24		24		24	mA
A #/ A	Insuit transition rise or fall rate	V <sub>CC</sub> = 1.5 V to 3 V		50		50		50	201
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 3.6 V to 5.5 V		20		20		20	ns/V

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		Vcc	T <sub>A</sub> = 2	5°C	–55°( 125		–40°C to 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX		
			1.5 V	1.4		1.4		1.4		
Vон		I <sub>OH</sub> = -50 μA	3 V	2.9		2.9		2.9		
			4.5 V	4.4		4.4		4.4		
	$V_I = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -4 \text{ mA}$	3 V	2.58		2.4		2.48		V
		I <sub>OH</sub> = -24 mA	4.5 V	3.94		3.7		3.8		
		$I_{OH} = -50 \text{ mA}^{\dagger}$	5.5 V			3.85				
		I <sub>OH</sub> = -75 mA†	5.5 V					3.85		
			1.5 V		0.1		0.1		0.1	
		I <sub>OL</sub> = 50 μA	3 V		0.1		0.1		0.1	
			4.5 V		0.1		0.1		0.1	
VOL	$V_I = V_{IH} \text{ or } V_{IL}$	I <sub>OL</sub> = 12 mA	3 V		0.36		0.5		0.44	V
		I <sub>OL</sub> = 24 mA	4.5 V		0.36		0.5		0.44	
		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V				1.65		1	
		I <sub>OL</sub> = 75 mA <sup>†</sup>	5.5 V						1.65	
I	$V_I = V_{CC}$ or GND		5.5 V		±0.1		±1		±1	μA
ICC	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V		8		160		80	μA
Ci					10		10		10	pF

<sup>†</sup> Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.



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# switching characteristics over recommended operating free-air temperature range, $V_{CC} = 1.5 \text{ V}$ , $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C to 125°C		–40°C to 85°C		UNIT	
		(001F01)	MIN N	ЛАХ	MIN	MAX		
<sup>t</sup> PLH	D	Y		169		152	ns	
<sup>t</sup> PHL	В	T		169		152	ns	
<sup>t</sup> PLH		W		186		169	ns	
<sup>t</sup> PHL	D	vv		186		169	115	
<sup>t</sup> PLH		Y		228		207	ns	
<sup>t</sup> PHL	A, B, or C	Γ		228	207		115	
<sup>t</sup> PLH	A, B, or C	W		245		223		
<sup>t</sup> PHL	A, B, 01 C	vv		245		223	ns	
<sup>t</sup> PLH	G	Y		153		139		
<sup>t</sup> PHL	6	Ť		153		139	ns	
<sup>t</sup> PLH	G	\A/		169		153		
<sup>t</sup> PHL	G	W		169		153	ns	

switching characteristics over recommended operating free-air temperature range,  $V_{CC}$  = 3.3 V  $\pm$  0.3 V,  $C_L$  = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55° 125		–40°C to 85°C		UNIT
	(INFUT)	(001401)	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	D	Y	4.7	18.9	4.9	17.1	
<sup>t</sup> PHL	B	T	4.7	18.9	4.9	17.1	ns
<sup>t</sup> PLH		W	5.2	20.9	5.4	19	ns
<sup>t</sup> PHL	D	vv	5.2	20.9	5.4	19	115
<sup>t</sup> PLH		Y	6.4	25.5	6.6	23.2	ns
<sup>t</sup> PHL	A, B, or C	Ť	6.4	25.5	6.6	23.2	115
<sup>t</sup> PLH	A, B, or C	W	6.9	27.4	7.1	24.9	ns
<sup>t</sup> PHL	A, B, 01 C		6.9	27.4	7.1	24.9	115
<sup>t</sup> PLH	G	Y	4.3	17.1	4.4	15.5	
<sup>t</sup> PHL	G	, i	4.3	17.1	4.4	15.5	ns
<sup>t</sup> PLH	G	W	4.7	18.9	4.9	17.2	
<sup>t</sup> PHL	G	vv	4.7	18.9	4.9	17.2	ns



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# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

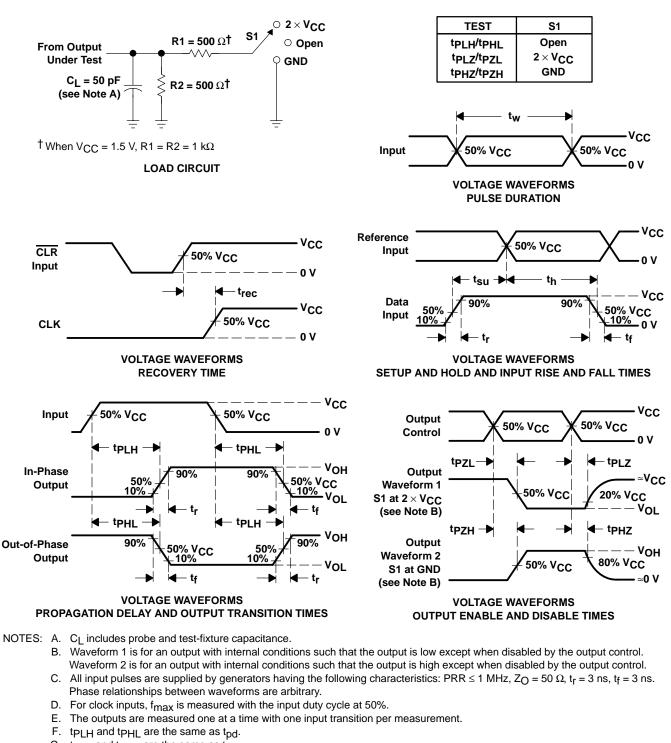
PARAMETER	FROM (INPUT)		–55° 125		–40°C to 85°C		UNIT
		(001-01)	MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	D	Y	3.4	13.5	3.5	12.3	ns
<sup>t</sup> PHL	ط	T	3.4	13.5	3.5	12.3	115
<sup>t</sup> PLH	5	W	3.7	14.9	3.8	13.5	ns
<sup>t</sup> PHL	D			14.9	3.8	13.5	115
<sup>t</sup> PLH		Y	4.6	18.2	4.7	16.5	ns
<sup>t</sup> PHL	A, B, or C	ľ	4.6	18.2	4.7	16.5	115
<sup>t</sup> PLH	A, B, or C	W	4.9	19.6	5.1	17.8	ns
<sup>t</sup> PHL	A, B, 01 C	vv	4.9	19.6	5.1	17.8	115
<sup>t</sup> PLH	G	Y	3.1	12.2	3.1	11.1	
<sup>t</sup> PHL	5	G		12.2	3.1	11.1	ns
<sup>t</sup> PLH	G	10/	3.4	13.5	3.5	12.3	
<sup>t</sup> PHL	G W -		3.4	13.5	3.5	12.3	ns

### operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = $25^{\circ}$ C

	PARAMETER	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	120	pF

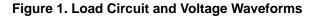


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PARAMETER MEASUREMENT INFORMATION

- G. tpzL and tpzH are the same as ten.
- H. tpLz and tpHz are the same as tdis.
- I. All parameters and waveforms are not applicable to all devices.





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### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CD74AC151E	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74AC151EE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74AC151M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC151M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74AC151M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. **TBD**: The Pb-Free/Green conversion plan has not been defined.

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**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

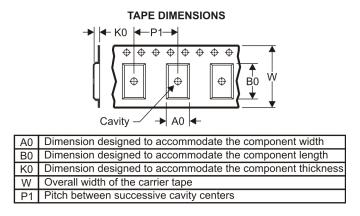
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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### TAPE AND REEL INFORMATION





### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal	
-----------------------------	--

Device	Package Type	Package Drawing	Pins		Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC151M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1



# PACKAGE MATERIALS INFORMATION

19-Mar-2008

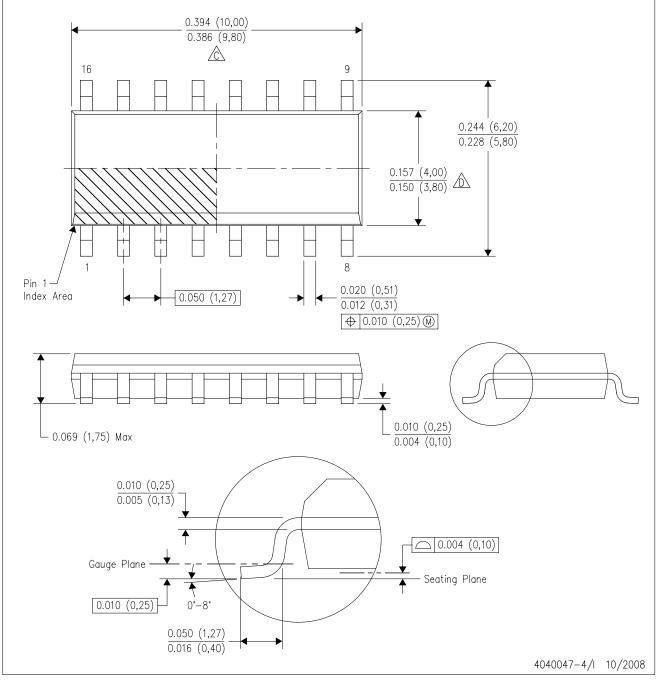


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74AC151M96	SOIC	D	16	2500	333.2	345.9	28.6

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

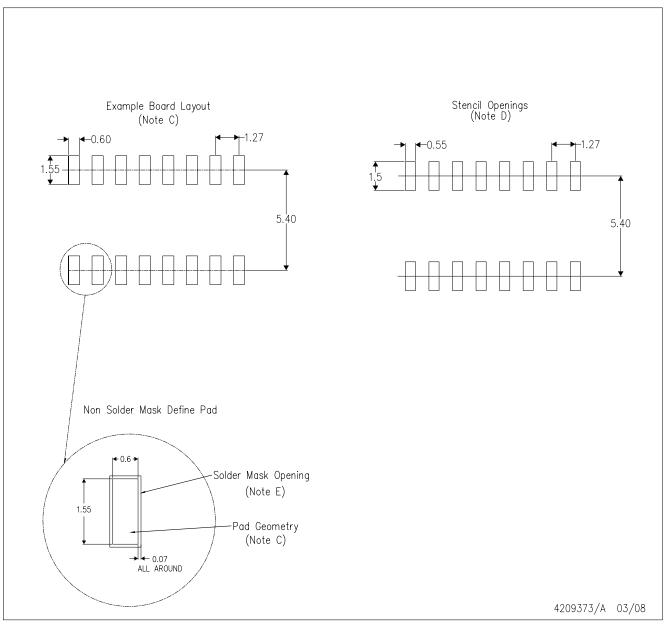
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AC.



D(R-PDSO-G16)



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
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